

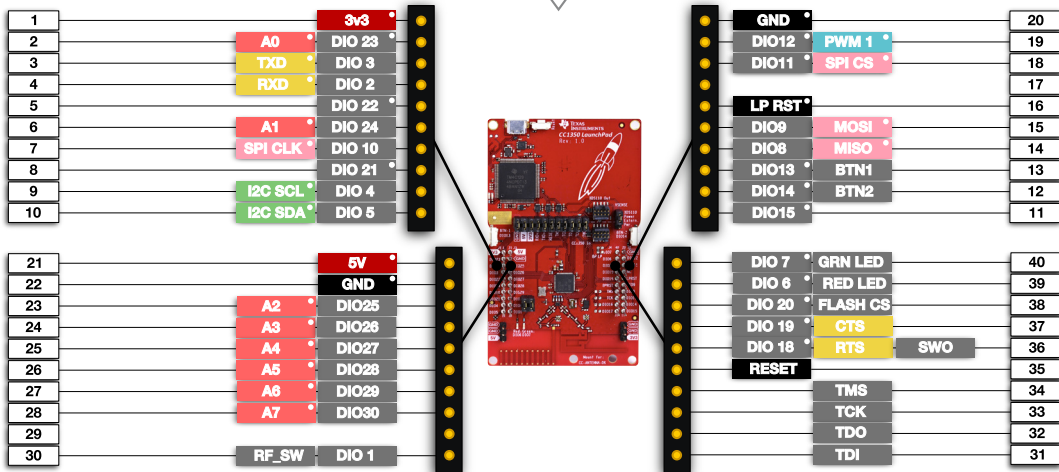


CC1350 LaunchPad™

// wireless microcontroller development kit for rapid prototyping.

LAUNCHXL-CC1350

○ Pin aligns with BoosterPack pinout standard.
Make your own BoosterPack @ www.ti.com/byob



Launch Your Design @ dev.ti.com/launchxl-cc1350

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